

Press Release

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Quik-Pak Completes New Expansion

San Diego, CA, April 16, 2009, - Quik-Pak, a division of Delphon Industries and leader in quick-turn integrated circuit (IC) prototype packaging, wafer processing, and advanced assembly services announced the completion of its new expanded facility today.

The company has added 5,800 sq ft of new clean manufacturing space which houses advanced substrate manufacturing and IC package assembly operations. The new expansion includes dedicated photolithography and crystal cutting and polishing rooms. New products and services include CZT, CT and HgI radiation detectors, laser micro-machining and flip-chip I.C. assembly.

"We are excited with the opportunities this latest expansion provides us, not to mention the increased elbow room", says Steve Swendrowski, General Manager of Quik-Pak. "We are now able to

cut, polish and metalize a wide variety of crystal materials for our radiation detector products. In addition, we have a laminate press and screen printing areas that can create high performance substrates to virtually any thickness."

About Quik-Pak:

The company specializes in open-cavity plastic packages and assembly in 24 hours or less. A limitless array of open-cavity packages are available with no minimum quantity and can be provided as part of a turnkey assembly solution along with backgrinding, wafer dicing, die/wire bonding, laser micromachining, detector array processing, remolding and marking/branding. Custom assembly services are also offered for ceramic packages, chip-on-board, stacked die, MEMS, etc. Quik-Pak's unique offerings deliver faster time to market and reduced prototype costs for new devices, while providing excellent flexibility, quality and customer service.

For further information:

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